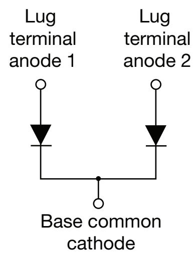
HEXFRED®
Ultrafast Soft Recovery Diode, 210 A

TO-244



FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced snubbing

DESCRIPTION / APPLICATIONS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dI_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	210 A
V_R	600 V
$I_{F(DC)}$ at T_C	120 A at 100 °C
Package	TO-244
Circuit configuration	Two diodes common cathode

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V_R		600	V
Continuous forward current	I_F	T_C = 25 °C	235	A
		T_C = 100 °C	120	
Single pulse forward current	I_{FSM}	Limited by junction temperature	600	
Non-repetitive avalanche energy	E_{AS}	L = 100 µH, duty cycle limited by maximum T_J	2.2	mJ
Maximum power dissipation	P_D	T_C = 25 °C	463	W
		T_C = 100 °C	185	
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +150	°C

ELECTRICAL SPECIFICATIONS PER LEG (T_J = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I_R = 100 µA		600	-	-	V
Maximum forward voltage	V_{FM}	I_F = 105 A	See fig. 1	-	1.38	1.9	
		I_F = 210 A		-	1.6	2.25	
		I_F = 105 A, T_J = 125 °C		-	1.3	1.56	
Maximum reverse leakage current	I_{RM}	T_J = 125 °C, V_R = 480 V	See fig. 2	-	1.8	6.0	mA
Junction capacitance	C_T	V_R = 200 V	See fig. 3	-	200	300	pF
Series inductance	L_S	From top of terminal hole to mounting plane		-	6.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNITS**
Reverse recovery time (fig. 5)	t_{rr}	I_F = 1.0 A, dI_F/dt = 200 A/μs, V_R = 30 V		-	35	-	ns
		T_J = 25 °C	I_F = 105 A dI_F/dt = 200 A/μs V_R = 200 V	-	90	140	
		T_J = 125 °C		-	160	240	
Peak recovery current (fig. 6)	I_{RRM}	T_J = 25 °C		-	10	18	A
		T_J = 125 °C		-	15	30	
Reverse recovery charge (fig. 7)	Q_{rr}	T_J = 25 °C		-	450	1300	nC
		T_J = 125 °C		-	1200	3600	
Peak rate of recovery current (fig. 8)	$dI_{(rec)M}/dt$	T_J = 25 °C		-	310	-	A/μs
		T_J = 125 °C		-	240	-	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNITS**
Maximum junction and storage temperature range		T_J, T_{Stg}	-55	-	150	°C
Thermal resistance, junction to case	per leg	R_{thJC}	-	-	0.27	°C/W K/W
	per module		-	-	0.135	
Typical thermal resistance, case to heatsink		R_{thCS}	-	0.10	-	
Weight			-	68	-	g
			-	2.4	-	oz.
Mounting torque [(1)]			30 (3.4)	-	40 (4.6)	lbf · in (N · m)
Mounting torque center hole			12 (1.4)	-	18 (2.1)	
Terminal torque			30 (3.4)	-	40 (4.6)	
Vertical pull			-	-	80	lbf · in
2" lever pull			-	-	35	

Note

[(1)] Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached

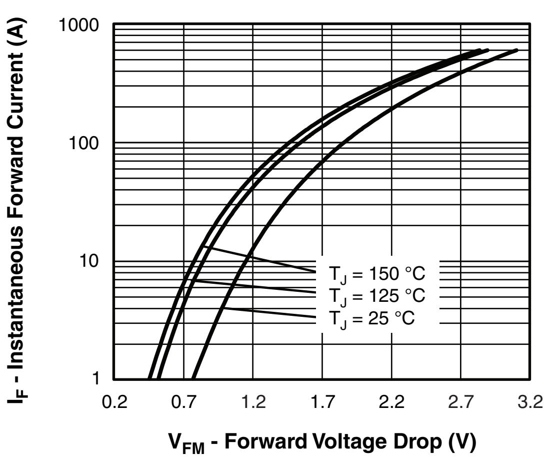


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

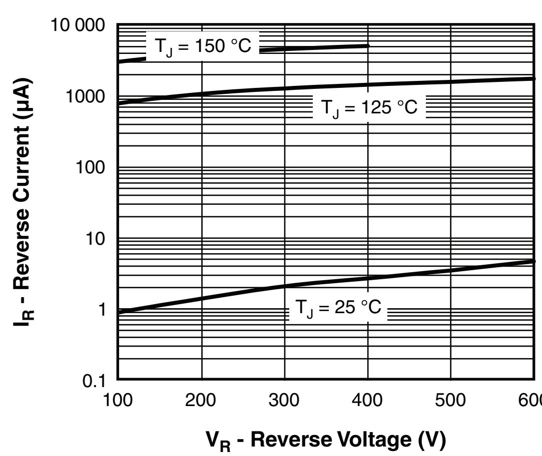


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

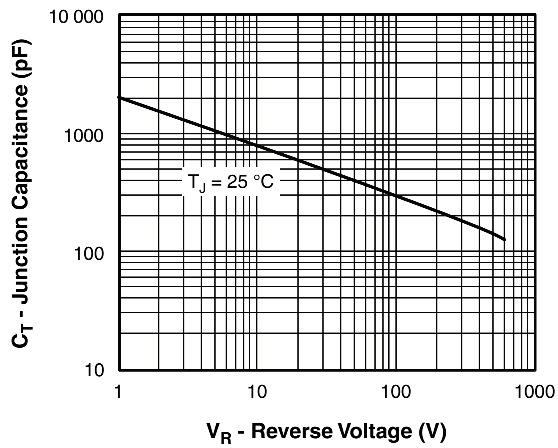


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

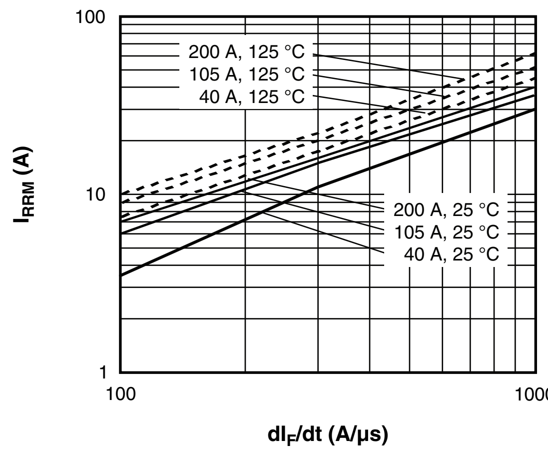


Fig. 6 - - Typical Recovery Current vs. dI_F/dt (Per Leg)

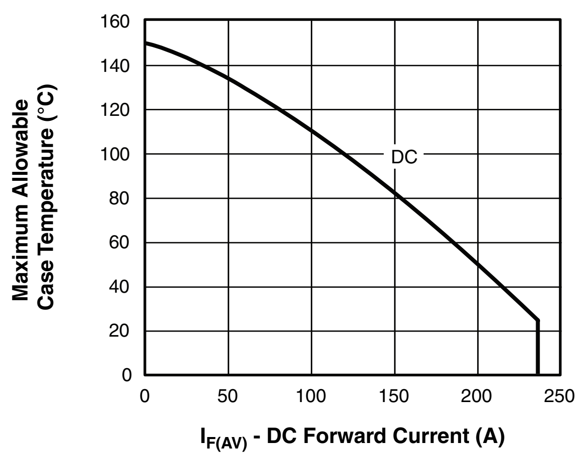


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

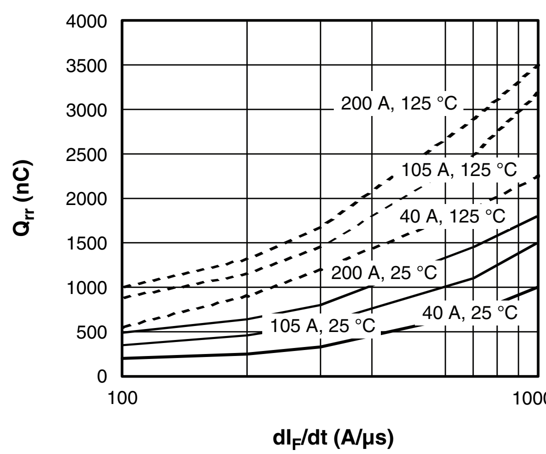


Fig. 7 - - Typical Stored Charge vs. dI_F/dt (Per Leg)

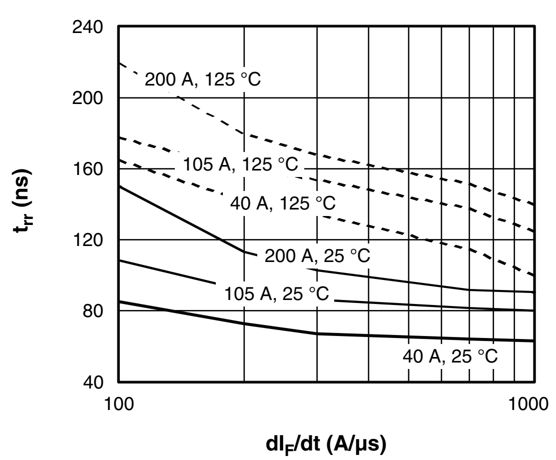


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt (Per Leg)

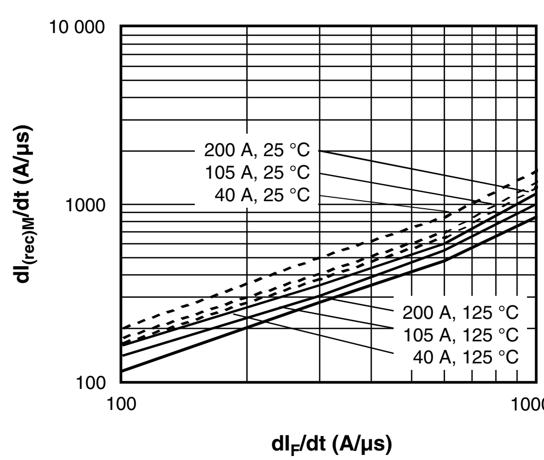


Fig. 8 - - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)

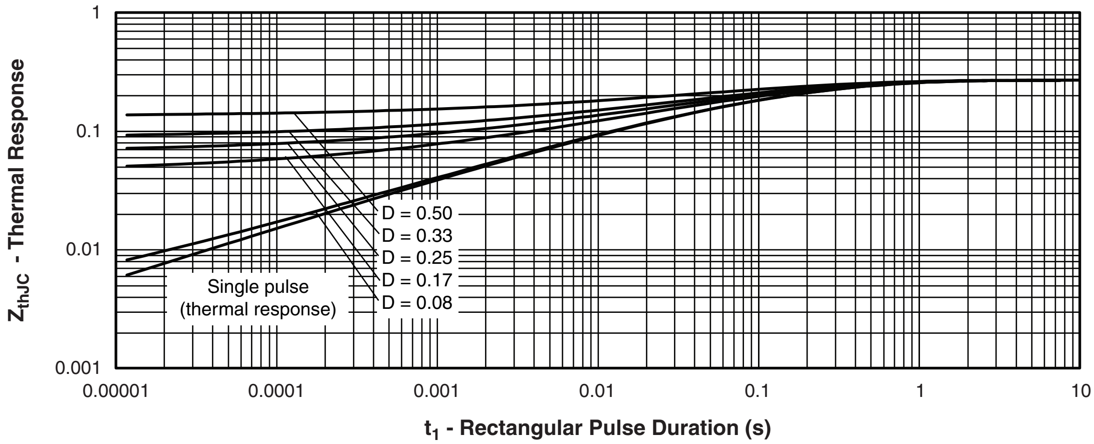


Fig. 9 - - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

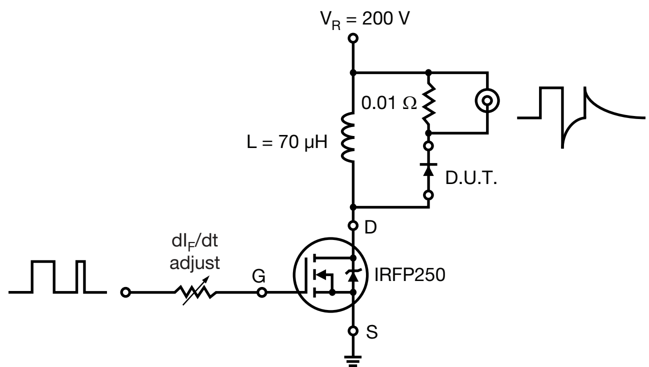
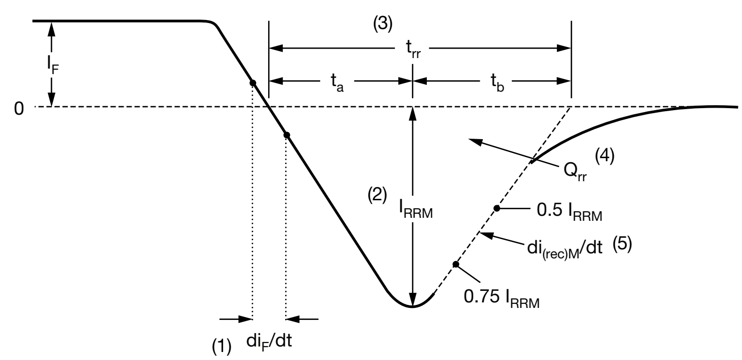


Fig. 10 - - Reverse Recovery Parameter Test Circuit



(1) di_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions

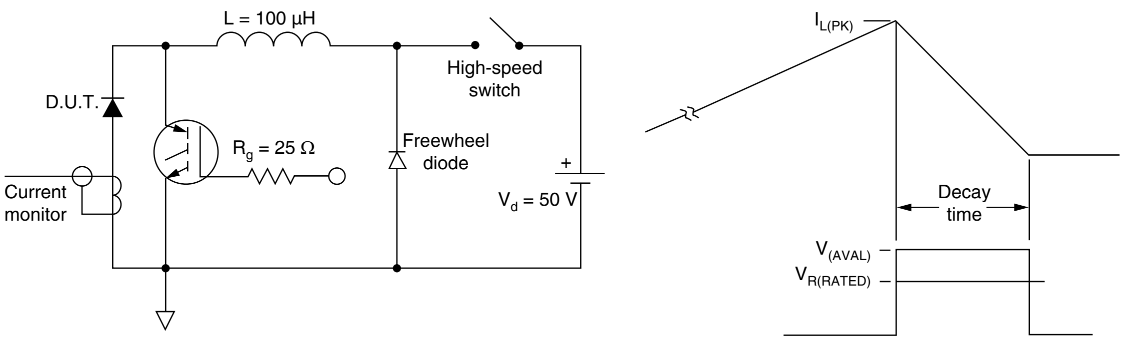


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

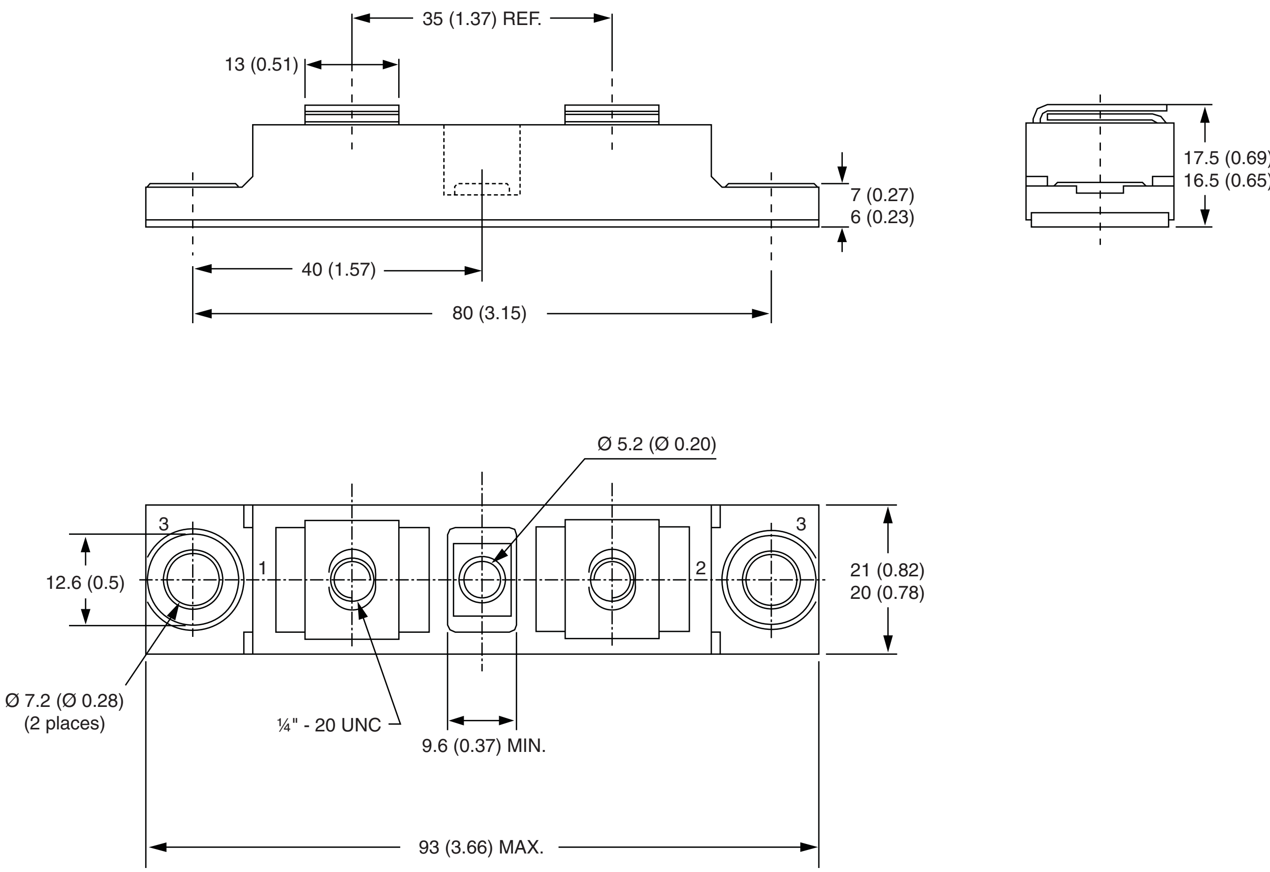
Device code	VS-	HFA	210	NJ	60	C	PbF
	1	2	3	4	5	6	7

1 - Vishay Semiconductors product
2 - HEXFRED® family, electron irradiated
3 - Average current rating
4 - NJ = TO-244
5 - Voltage rating (60 = 600 V)
6 - C = two diodes common cathode
7 - Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95021

TO-244

DIMENSIONS in millimeters (inches)



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